Fine Inductors
Fastron

Statement

1.)

Directive 2003/11/EC amending for the 24th. time Council Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations (pentabromodiphenyl ether, octabromodiphenyl ether).

Products manufactured and supplied by FASTRON do not contain the below substances respectively do not contain these substances in concentrations higher than 0.1% by mass and comply with the EU Directive 2003/11/EC of 6 February 2003.

- Pentabromodiphenyl ether
- Octabromodiphenyl ether

2.)

Directive 2002/95/EC On The Restriction Of The Use Of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS).

Products manufactured and supplied by FASTRON comply with EU Directive 2002/95/EC of 27 January 2003.

Until the limits of the substances covered by this Directive are finaly defined, we use the limits indicated below:

Lead:	1000 ppm weight in homogenous materials
Mercury:	1000 ppm weight in homogenous materials
Cadium:	100 ppm weight in homogenous materials
Hexavalent Chromium:	1000 ppm weight in homogenous materials
Polybrominated Biphenyls (PBB):	1000 ppm weight in homogenous materials
Polybrominated Diphenyls Ethers (PBDE):	1000 ppm weight in homogenous materials

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3.)

Directive 2000/53/EC on End of Life Vehicles

Products manufactured and supplied by FASTRON comply with EU Directive 2000/53/EC of 18 September 2000 taking account of "Commission Decision 2002/525/EC" of 27 June 2002 amending Anex II of the Directive.

4.)

Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEE)

Products manufactured and supplied by FASTRON do not contain substances covered by the EU Directive 2002/96/EC of 27 January 2003

5.)

Halogenated Substances

Products manufactured and supplied by FASTRON do not contain declarable halogenated substances (e.g. chlorinated hydrocarbons).

6.)

Lead Free Policy

Products from FASTRON are supplied with Lead Free leads/terminals apart from the following series:
PISL, PISM, PISN and PISR.

These series are supplied with Lead Free terminals but use a solder for high temperature containing more than 85% lead.
Lead Free means that a maximum concentration value up to 0.1% by weight is tolerated.
Resistance to soldering heat of our components; 260°C, 10sec. according to IEC 60068-2-20, test Tb.

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Lead-Free and RoHs Information for FASTRON SDN BHD Products

Product-Family	Series	"Leadfree" (yes/no)	"lead free" since (date)	already RoHS-compliant (yes/no)	RoHS-compliant since (date)	Resitance to soldering heat				Plating / Metallization of Terminals / Leads
						IEC 60068-2-20 (Wave Soldering)	IEC 60068-2-58 (Dip test)	JEDEC 20C (Reflow)	Maximum Solder Temperature	
Chip Inductors (Wire Wound - open)	0402AS 0603AS 0805AS/AQ 0805F 1008AS/F 1206AS 1206F	yes	2000	yes	2000	n/a	yes	yes	260°C, 10sec.	Ceramic: W, Ni, Gold-flash Ferrite: Ag, Ni, Gold-flash
	1210AS 1210F 1812AS 1812AF	yes	2006	yes	2006	n/a	yes	yes	260°C, 10sec.	Sn 99,9
Chip Inductors Multilayer	0402MLA 0603MLA 0805MLA	yes	2003	yes	2003	n/a	yes	yes	260°C, 10sec.	Sn 99,9
Chip Inductors Multilayer (shielded)	0402MLF 0603MLF 0805MLF 1206MLF	yes	2003	yes	2003	n/a	yes	yes	260°C, 10sec.	Sn 99,9
Transponder Coils	4408 AF	yes	2005	yes	2005	yes	yes	yes	260°C, 10sec.	Gold-flash
Moulded Inductors	CCSH CCSS	yes	Nov 2003	yes	Nov 2003	n/a	yes	yes	260°C, 10sec.	Sn 99,9
Leaded Inductors	MICC	yes	Nov 2003	yes	Nov 2003	yes	n/a	n/a	260°C, 10sec.	Sn 99,9
	MICC-1R0K...-150K	yes	July 2005	yes	July 2005					
	MICCS	yes	Nov 2003	yes	Nov 2003					
	SMCC	yes	Nov 2003	yes	Nov 2003					
	MSMCC	yes	Nov 2003	yes	Nov 2003					
	MECC	yes	July 2005	yes	July 2005					
	LACC	yes	Nov 2003	yes	Nov 2003					
	HACC	yes	Nov 2003	yes	Nov 2003					
	HACC-1R0K...-2R7K	yes	July 2005	yes	July 2005					
	HACC- 4R7K...-8R2K	yes	July 2005	yes	July 2005					
	HBCC	yes	Nov 2003	yes	Nov 2003					
	HBCC-1R0K...-8R2K	yes	July 2005	yes	July 2005					
	HCCC	yes	Nov 2003	yes	Nov 2003					
	VHBCC	yes	Nov 2003	yes	Nov 2003					
	XHBCC	yes	Nov 2003	yes	Nov 2003					
Suppresion Coils	MISC SMSC MESC 77A 50A	yes	Nov 2003	yes	Nov 2003	yes	n/a	n/a	260°C, 10sec.	Sn 99,9
	LASC SSSC MSSC LSSC	yes	Oct2003	yes	yes	yes	n/a	n/a	260°C, 10sec.	Sn 99,9
Plugable Inductors (shielded)	07P; 07P/F 09P; 09P/F 11P 07M; 07MFG	yes	Nov 2003	yes	Nov 2003	yes	n/a	n/a	260°C, 10sec.	Sn 99,9

Product-Family	Series	"Leadfree" (yes/no)	"lead free" since (date)	already RoHS-compliant (yes/no)	RoHS-compliant since (date)	Resitance to soldering heat				Plating / Metallization of Terminals / Leads
						IEC 60068-2-20 (Wave Soldering)	IEC 60068-2-58 (Dip test)	JEDEC 20C (Reflow)	Maximum Solder Temperature	
Wide Band Chokes	06H	yes	2005	yes	2005	yes	n/a	n/a	260°C, 10sec.	Sn 99,9
	Beads							n/a	260°C, 10sec.	Sn 99,9
SMD Power Inductors (shielded)	PISG	yes	2001	yes	2001	n/a	yes	yes	260°C, 10sec.	Ag, Pd, Gold-flash
	SPISG	yes	2006	yes	2006	n/a	n/a	yes	260°C, 10sec.	Ag, Pd, Gold-flash
	PISL PISM PISN PISR	no, please see comment below 1.)	n/a	yes	Aug 2004	n/a			260°C, 10sec.	Sn 99,9
	SPISM		n/a	yes	2006	n/a			260°C, 10sec.	Sn 99,9
	PIS 2408 PIS 2416 PIS 2812 PIS 2816 PIS 4716 PIS 4720 PIS 4728	yes	2006	yes	2006	n/a	n/a	yes	260°C, 10sec.	Sn 99,9

1.) 1.) Our series PISL, PISM, PISN and PISR are already supplied with lead free terminals but use a solder for high temperatures containing more than 85% lead

Please note:

Until the limits of the substances covered by this Directive are finally defined we use the limits indicated below:

Lead:	1000 ppm weight in homogeneous materials
Mercury:	1000 ppm weight in homogeneous materials
Cadmium:	100 ppm weight in homogeneous materials
Hexavalent Chromium:	1000 ppm weight in homogeneous materials
Polybrominated Biphenyls (PBB):	1000 ppm weight in homogeneous materials
Polybrominated Diphenyl Ethers (PBDE):	1000 ppm weight in homogeneous materials

Date: November 08, 2006